

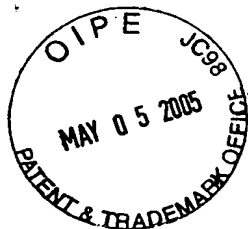
VIA FAX CONFIRMATION BY AIR MAIL

April 19, 2005

CONFIRMATION

VENABLE LLP.

575 7th Street, NW
Washington, D.C.
20004-1601, U.S.A



Re: U.S. Patent Application No.09/053,040
Oki Electric Industry Co., Ltd.
YOUR REF : 31759-138000NNK
OUR REF: FOKI97026D1/US



HAZUKI

INTERNATIONAL YOTSUYA

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Dear Sirs,

Thank you for your letter of March 17, 2005, reporting receiving the Notice of Allowance for the above case.

First of all, we ask you to pay the issue fee for the above-identified case before the due date, i.e., May 31, 2005.

Second, we ask you to amend the claim 9 in accordance with the attached instruction on or before paying the issue fee.

Also please be informed that our client hopes to have not only Letters Patent but also two soft copies thereof. Therefore we ask you to let us have soft copy of Letters Patent.

Please acknowledge receipt of this letter by return.

We appreciate your cooperation.

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Yours sincerely,
**HAZUKI INTERNATIONAL
YOTSUYA**

RECEIVED

APR 27 2005

Finnegan, Henderson, Farabow,
Garrett & Dunner, L.L.P.

YK/yt

Seiji Tamura
for Yoshiaki KAMEYA

- Please amend following minor error in claim 9.

9. A management method for a production process of a semiconductor device comprising:
providing information on production management consisting of a two-dimensional code pattern and another pattern both of which are disposed on an outer surface of a resin sealment of a semiconductor device having a semiconductor chip and the resin for sealing the semiconductor chip;
recognizing a product name of the device from said another pattern;
reading out the two dimensional code pattern provided on ~~the semiconductor chips~~ the outer surface of the resin sealment of the semiconductor device in an information read device; and
using the read-out information to perform management of production processes.